

## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **A SEMICONDUCTOR INTEGRATED CIRCUIT HAVING COMPRESSION CIRCUITRY FOR COMPRESSING TEST DATA, AND THE TEST SYSTEM AND METHOD UTILIZING THE SEMICONDUCTOR INTEGRATED CIRCUIT**; the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, Section 1.56.

I hereby claim the benefit under Title 35 of the United States Code, Section 120 to which I am entitled and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35 of the United States Code, Section 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, Section 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

Inventor's Full Name: Roland Ochoa  
(First) (MI) (Last)

Inventor's Signature: *Roland Ochoa* Date: 12-9-94

Citizenship: United States

Post Office Address: 4185 Kilarney

Boise, Idaho 83704-3334

City, State and  
Country of Residence Boise, Idaho United States of America

Inventor's Full Name: Gregory L. Cowan  
(First) (MI) (Last)

Inventor's Signature: *Gregory L. Cowan* Date: 9-DEC-94

Citizenship: United States

Post Office Address: 1554 Riverstone Lane, #304

Boise, Idaho 83706

City, State and  
Country of Residence Boise, Idaho United State of America

10940010-037601

Inventor's Full Name: Roland Ochoa  
(First) (MI) (Last)

Inventor's Signature: Roland Ochoa Date: 12-9-94

Citizenship: United States

Post Office Address: 4185 Kilarney

Boise, Idaho 83704-3334

City, State and  
Country of Residence Boise, Idaho United States of America

Inventor's Full Name: Gregory L. Cowan  
(First) (MI) (Last)

Inventor's Signature: Gregory L. Cowan Date: 9-DEC-94

Citizenship: United States

Post Office Address: 1554 Riverstone Lane, #304

Boise, Idaho 83706

City, State and  
Country of Residence Boise, Idaho United State of America



**SUPPLEMENTAL DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)**

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **A SEMICONDUCTOR INTEGRATED CIRCUIT HAVING COMPRESSION CIRCUITRY FOR COMPRESSING TEST DATA, AND THE TEST SYSTEM AND METHOD FOR UTILIZING THE SEMICONDUCTOR INTEGRATED CIRCUIT**, the specification of which (check one):

☐ is attached hereto.

☒ was filed on October 20, 1998 as United States application serial no. 09/175,518.

☐ was filed on \_\_\_\_\_ as PCT international application no. \_\_\_\_\_ and was amended under PCT Article 19 on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

(number)	(country)	(day/month/year filed)	Priority Claimed	
_____	_____	_____	Yes	No
_____	_____	_____	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

08/881,946  
(application serial no.)

June 25, 1997  
(filing date)

Patented - 5,864,565  
(status - pending, patented or abandoned)

08/353,404  
(application serial no.)

December 9, 1994  
(filing date)

Abandoned  
(status - pending, patented or abandoned)

08/077,182  
(application serial no.)

June 15, 1993  
(filing date)

Abandoned  
(status - pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

\_\_\_\_\_ (provisional application no.)

\_\_\_\_\_ (filing date)

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012  
Joseph A. Walkowski, Reg. No. 28,765  
Edgar R. Cataxinos, Reg. No. 39,931  
Brick G. Power, Reg. No. 38,581  
Devin R. Jensen, Reg. No. 44,805  
David L. Stott, Reg. No. 43,937  
Michael L. Lynch, Reg. No. 30,871

William S. Britt, Reg. No. 20,969  
James R. Duzan, Reg. No. 28,393  
Kent S. Burningham, Reg. No. 30,453  
Kenneth B. Ludwig, Reg. No. 42,814  
Eleanor V. Goodall, Reg. No. 35,162  
Kerry D. Tweet, Reg. No. 45,959  
Charles B. Brantley II, Reg. No. 38,086

Laurence B. Bond, Reg. No. 30,549  
Allen C. Turner, Reg. No. 33,041  
Stephen R. Christian, Reg. No. 32,687  
Paul C. Oestreich, Reg. No. 44,983  
Samuel E. Webb, Reg. No. 44,394  
Bradley B. Jensen, Reg. No. 46,801

Address all correspondence to:

Joseph A. Walkowski, telephone no. (801) 532-1922.  
**TRASK BRITT**  
P.O. BOX 2550  
Salt Lake City, Utah 84110

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: Roland Ochoa

Inventor's signature \_\_\_\_\_

Residence: Boise, Idaho

Citizenship: USA

Post Office Address: 4185 Kilarney, Boise, ID 83704-3334

Date

2-22-01

## DECLARATION FOR PATENT APPLICATION

(continuation page)

Invention title: A SEMICONDUCTOR INTEGRATED CIRCUIT HAVING COMPRESSION CIRCUITRY FOR COMPRESSING TEST DATA, AND THE TEST SYSTEM AND METHOD FOR UTILIZING THE SEMICONDUCTOR INTEGRATED CIRCUIT

Inventor name(s) appearing on first declaration page: Roland Ochoa

☒ Additional original, first and joint inventor(s):

Full name of second joint inventor: Gregory L. Cowan

Inventor's signature

Residence: Boise, Idaho

Citizenship: USA

Post Office Address: 1554 Riverstone Lane, #304, Boise, ID 83706

Date

23-FEB-2001

Full name of third joint inventor: Kim M. Pierce

Inventor's signature

Residence: Meridian, Idaho

Citizenship: USA

Post Office Address: 1064 East Cayman Drive, Meridian, ID 83642

Date

104280-01004650

# SUPPLEMENTAL DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **A SEMICONDUCTOR INTEGRATED CIRCUIT HAVING COMPRESSION CIRCUITRY FOR COMPRESSING TEST DATA, AND THE TEST SYSTEM AND METHOD FOR UTILIZING THE SEMICONDUCTOR INTEGRATED CIRCUIT**, the specification of which (check one):

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Prior foreign/PCT application(s):

			Priority Claimed	
(number)	(country)	(day/month/year filed)	Yes	No
_____	_____	_____	_____	_____
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Full name of first joint inventor: Roland Ochoa

Inventor's signature \_\_\_\_\_ Date \_\_\_\_\_

Residence: Boise, Idaho

Citizenship: USA

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DECLARATION FOR PATENT APPLICATION  
(continuation page)

Invention title: A SEMICONDUCTOR INTEGRATED CIRCUIT HAVING COMPRESSION CIRCUITRY FOR COMPRESSING TEST DATA, AND THE TEST SYSTEM AND METHOD FOR UTILIZING THE SEMICONDUCTOR INTEGRATED CIRCUIT

Inventor name(s) appearing on first declaration page: Roland Ochoa

☒ Additional original, first and joint inventor(s):

Full name of second joint inventor: Gregory L. Cowan

Inventor's signature \_\_\_\_\_ Date \_\_\_\_\_

Residence: Boise, Idaho

Citizenship: USA

Post Office Address: 1554 Riverstone Lane, #304, Boise, ID 83706

Full name of third joint inventor: Kim M. Pierce

Inventor's signature Kim M. Pierce Date March 6, 2001

Residence: Meridian, Idaho

Citizenship: USA

Post Office Address: 1064 East Cayman Drive, Meridian, ID 83642

FOI 200-01004660